

2. Electrical Specifications

Table 2.1. Electrical Specifications
 $V_{DD} = 1.8\text{ V}, 2.5\text{ V or }3.3\text{ V} \pm 5\%$, $T_A = -40\text{ to }85\text{ }^\circ\text{C}$

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Temperature Range	T_A		-40	—	85	$^\circ\text{C}$
Frequency Range	F_{CLK}	LVPECL, LVDS, CML	0.2	—	3000	MHz
		HCSL	0.2	—	400	MHz
		CMOS, Dual CMOS	0.2	—	250	MHz
Supply Voltage	V_{DD}	3.3 V	3.135	3.3	3.465	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
Supply Current	I_{DD}	LVPECL (output enabled)	—	120	170	mA
		LVDS/CML (output enabled)	—	100	140	mA
		HCSL (output enabled)	—	95	140	mA
		HCSL-Fast (output enabled)	—	103	152	mA
		CMOS (output enabled)	—	95	145	mA
		Dual CMOS (output enabled)	—	105	155	mA
		Tristate Hi-Z (output disabled)	—	83	—	mA
Temperature Stability ¹		-40 to 85 $^\circ\text{C}$	-20	—	20	ppm
Rise/Fall Time (20% to 80% V_{PP})	T_R/T_F	LVPECL/LVDS/CML	—	—	350	ps
		CMOS / Dual CMOS ($C_L = 5\text{ pF}$)	—	0.5	1.5	ns
		HCSL, $F_{CLK} > 50\text{ MHz}$	—	—	550	ps
		HCSL-Fast, $F_{CLK} > 50\text{ MHz}$	—	—	275	ps
Duty Cycle	D_C	All formats	45	—	55	%
Output Enable (OE) Frequency Select (FS0, FS1) ²	V_{IH}		$0.7 \times V_{DD}$	—	—	V
	V_{IL}		—	—	$0.3 \times V_{DD}$	V
	T_D	Output Disable Time, $F_{CLK} > 10\text{ MHz}$	—	—	3	μs
	T_E	Output Enable Time, $F_{CLK} > 10\text{ MHz}$	—	—	20	μs
	T_{FS}	Settling Time after FS Change	—	—	10	ms
Powerup Time	t_{OSC}	Time from $0.9 \times V_{DD}$ until output frequency (F_{CLK}) within spec	—	—	10	ms
Powerup VDD Ramp Rate	V_{RAMP}	Fastest V_{DD} ramp rate allowed on startup	—	—	100	V/ms
LVPECL Output Option ³	V_{OC}	Mid-level	$V_{DD} - 1.42$	—	$V_{DD} - 1.25$	V
	V_O	Swing (diff, $F_{CLK} \leq 1.5\text{ GHz}$)	1.1	—	1.9	V_{PP}
		Swing (diff, $F_{CLK} > 1.5\text{ GHz}$) ⁶	0.55	—	1.7	V_{PP}

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
LVDS Output Option ⁴	V _{OC}	Mid-level (2.5 V, 3.3 V VDD)	1.125	1.20	1.275	V
		Mid-level (1.8 V VDD)	0.8	0.9	1.0	V
	V _O	Swing (diff, F _{CLK} ≤ 1.4 GHz)	0.6	0.7	0.9	V _{PP}
		Swing (diff, F _{CLK} > 1.4 GHz) ⁶	0.25	0.5	0.8	V _{PP}
HCSL Output Option ⁵ HCSL-Fast Output Option ⁵	V _{OH}	Output voltage high	660	800	850	mV
	V _{OL}	Output voltage low	-150	0	150	mV
	V _C	Crossing voltage	250	410	550	mV
CML Output Option (AC-Coupled)	V _O	Swing (diff, F _{CLK} ≤ 1.5 GHz) ⁶	0.6	0.8	1.0	V _{PP}
		Swing (diff, F _{CLK} > 1.5 GHz) ⁶	0.3	0.55	0.9	V _{PP}
CMOS Output Option	V _{OH}	I _{OH} = 8/6/4 mA for 3.3/2.5/1.8 V VDD	0.85 × V _{DD}	—	—	V
	V _{OL}	I _{OL} = 8/6/4 mA for 3.3/2.5/1.8 V VDD	—	—	0.15 × V _{DD}	V

Notes:

1. Min APR includes temperature stability, initial accuracy, load pulling, VDD variation, and aging for 20 yrs at 70 °C.
2. OE includes a 50 kΩ pull-up to VDD for OE active high, or includes a 50 kΩ pull-down to GND for OE active low. FS0 and FS1 pins each include a 50 kΩ pull-up to VDD.
3. R_{term} = 50 Ω to V_{DD} - 2.0 V (see Figure 4.1). Additional DC current from the output driver will flow through the 50 Ω resistors, resulting in a shift in common mode voltage. The measurements in this table have accounted for this.
4. R_{term} = 100 Ω (differential) (see Figure 4.2).
5. R_{term} = 50 Ω to GND (see Figure 4.2).
6. Refer to the figure below for Typical Clock Output Swing Amplitudes vs Frequency.

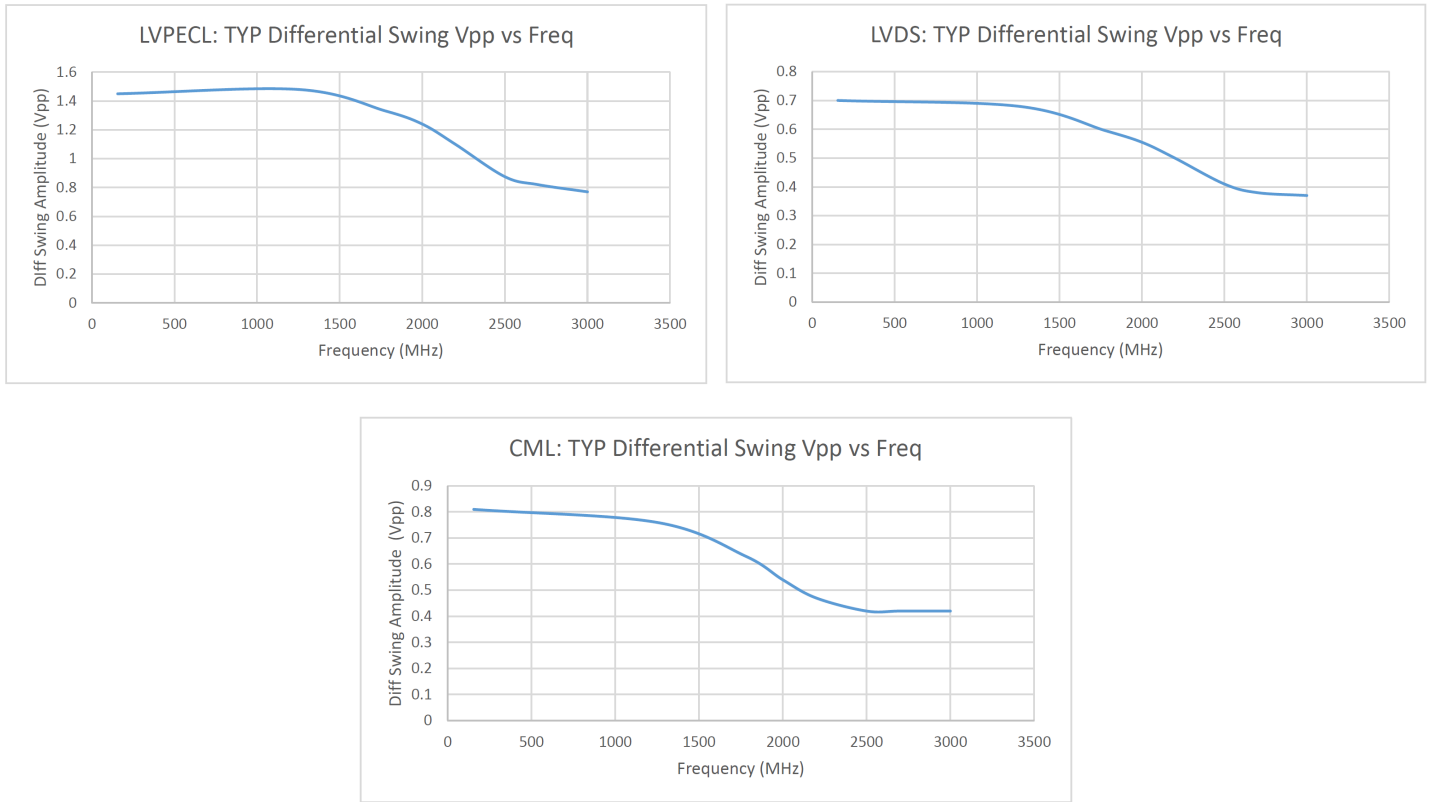


Figure 2.1. Typical Clock Output Swing Amplitudes vs. Frequency

Table 2.2. V_C Control Voltage InputV_{DD} = 1.8, 2.5 or 3.3 V ± 5%, T_A = -40 to 85 °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Control Voltage Range	V _C		0.1 x VDD	VDD/2	0.9 x VDD	V
Control Voltage Tuning Slope (V _c = 10% VDD to 90% VDD)	Kv	Positive slope, ordering option	60, 75, 105, 150, 180, 225			ppm/V
Kv Variation	Kv_var		—	—	±10	%
Control Voltage Linearity	LVC	Best Straight Line fit	-1.5	±0.5	+1.5	%
Modulation Bandwidth	BW		—	10	—	kHz
Vc Input Impedance	ZVC		500	—	—	kΩ

Table 2.3. Clock Output Phase Jitter and PSNRV_{DD} = 1.8 V, 2.5 or 3.3 V ± 5%, T_A = -40 to 85 °C

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Phase Jitter (RMS, 12 kHz - 20 MHz) ¹ All Differential Formats, F _{CLK} ≥ 200 MHz	ϕ _J	Kv = 60 ppm/V	—	100	150	fs
		Kv = 75 ppm/V	—	103	—	fs
		Kv = 105 ppm/V	—	110	—	fs
		Kv = 150 ppm/V	—	123	—	fs
		Kv = 180 ppm/V	—	132	—	fs
		Kv = 225 ppm/V	—	150	—	fs
Phase Jitter (RMS, 12 kHz - 20 MHz) ¹ All Diff Formats, 100 MHz ≤ F _{CLK} < 200 MHz	ϕ _J	Kv = 60 ppm/V	—	115	180	fs
		Kv = 75 ppm/V	—	118	—	fs
		Kv = 105 ppm/V	—	125	—	fs
		Kv = 150 ppm/V	—	138	—	fs
		Kv = 180 ppm/V	—	147	—	fs
		Kv = 225 ppm/V	—	165	—	fs
Phase Jitter (RMS, 12 kHz - 20 MHz) ¹ LVDS, F _{CLK} = 156.25 MHz	ϕ _J	Kv = 60 ppm/V	—	110	130	fs
		Kv = 75 ppm/V	—	113	—	fs
		Kv = 105 ppm/V	—	120	—	fs
		Kv = 150 ppm/V	—	133	—	fs
		Kv = 180 ppm/V	—	142	—	fs
		Kv = 225 ppm/V	—	160	—	fs
Phase Jitter (RMS, 12 kHz - 20 MHz) ¹ CMOS / Dual CMOS Formats	ϕ _J	10 MHz ≤ F _{CLK} < 250 MHz	—	200	—	fs

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Spurs Induced by External Power Supply Noise, 50 mVpp Ripple. LVDS 156.25 MHz Output	PSNR	100 kHz sine wave		-83		dBc
		200 kHz sine wave		-83		
		500 kHz sine wave		-82		
		1 MHz sine wave		-85		

Note:

1. Guaranteed by characterization. Jitter inclusive of any spurs.

Table 2.4. 3.2 x 5 mm Clock Output Phase Noise (Typical)

Offset Frequency (f)	156.25 MHz LVDS	200 MHz LVDS	644.53125 MHz LVDS	Unit
100 Hz	-73	-71	-60	dBc/Hz
1 kHz	-102	-102	-93	
10 kHz	-130	-128	-118	
100 kHz	-141	-139	-129	
1 MHz	-150	-148	-138	
10 MHz	-159	-160	-153	
20 MHz	-160	-162	-154	
Offset Frequency (f)	156.25 MHz LVPECL	200 MHz LVPECL	644.53125 MHz LVPECL	Unit
100 Hz	-72	-71	-60	dBc/Hz
1 kHz	-103	-101	-92	
10 kHz	-130	-127	-117	
100 kHz	-142	-139	-129	
1 MHz	-150	-148	-138	
10 MHz	-160	-162	-154	
20 MHz	-161	-162	-156	

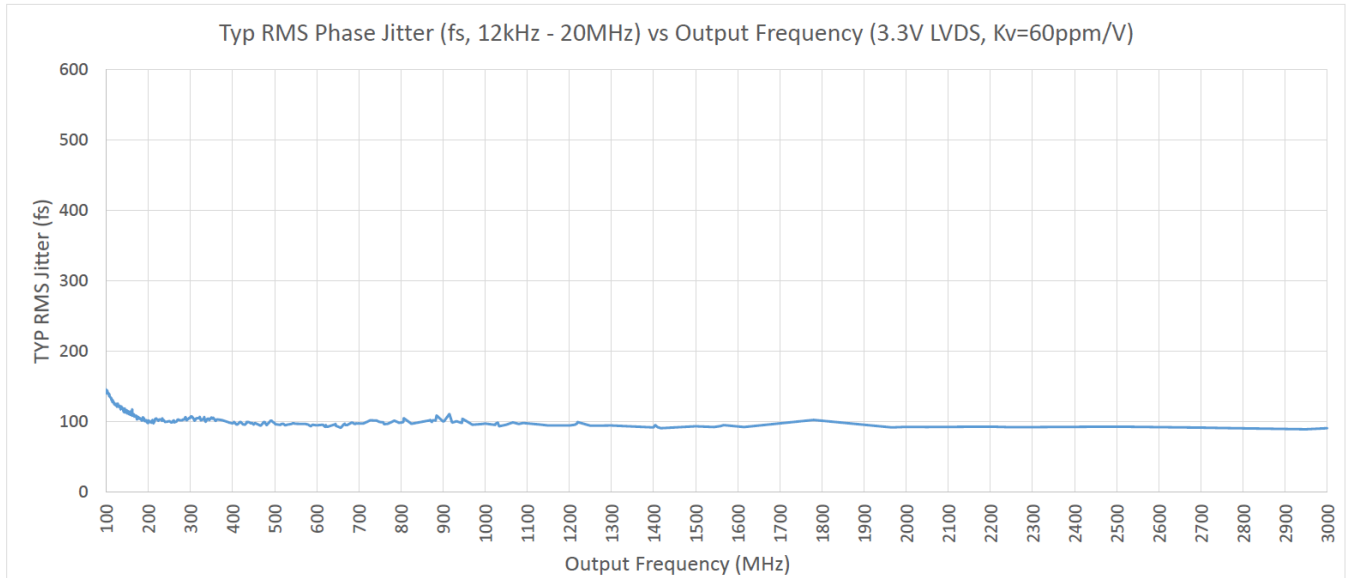


Figure 2.2. Phase Jitter vs. Output Frequency

Phase jitter measured with Agilent E5052 using a differential-to-single ended converter (balun or buffer). Measurements collected for >700 commonly used frequencies. Phase noise plots for specific frequencies are available using our free, online Oscillator Phase Noise Lookup Tool at <https://www.skyworksinc.com/en/Products/Timing-Oscillators>.

Table 2.5. Environmental Compliance and Package Information

Parameter	Test Condition
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Solderability	MIL-STD-883, Method 2003
Gross and Fine Leak	MIL-STD-883, Method 1014
Resistance to Solder Heat	MIL-STD-883, Method 2036
Moisture Sensitivity Level (MSL): 3.2 x 5, 5 x 7 packages	1
Moisture Sensitivity Level (MSL): 2.5 x 3.2 package	2
Contact Pads: 3.2x5, 5x7 packages	Au/Ni (0.3 - 1.0 μm / 1.27 - 8.89 μm)
Contact Pads: 2.5x3.2 packages	Au/Pd/Ni (0.03 - 0.12 μm / 0.1 - 0.2 μm / 3.0 - 8.0 μm)
Note:	
1. For additional product information not listed in the data sheet (e.g. RoHS Certifications, MDDS data, qualification data, REACH Declarations, ECCN codes, etc.), refer to our "Corporate Request For Information" portal found here: www.skyworksinc.com/quality .	

Table 2.6. Thermal Conditions¹

Max Junction Temperature = 125° C

Package	Parameter	Symbol	Test Condition	Value	Unit
2.5 x 3.2 mm 8-pin DFN ²	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	72	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	38	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	15	°C/W
3.2 x 5 mm 8-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	55	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	20	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	20	°C/W
5 x 7 mm 8-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	53	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	26	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	26	°C/W
Note:					
1. Based on PCB Dimensions: 4.5" x 7", PCB Thickness: 1.6 mm, Number of Cu Layers: 4.					
2. For best 2.5x3.2mm thermal performance, use 2 GND vias as shown in the Si5xxUC-EVB eval board layout					

Table 2.7. Absolute Maximum Ratings¹

Parameter	Symbol	Rating	Unit
Maximum Operating Temp.	T_{AMAX}	95	°C
Storage Temperature	T_S	-55 to 125	°C
Supply Voltage	V_{DD}	-0.5 to 3.8	°C
Input Voltage	V_{IN}	-0.5 to $V_{DD} + 0.3$	V
ESD HBM (JESD22-A114)	HBM	2.0	kV
Solder Temperature ²	T_{PEAK}	260	°C
Solder Time at T_{PEAK} ²	T_P	20–40	sec

Notes:

1. Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.
2. The device is compliant with JEDEC J-STD-020.

3. Dual CMOS Buffer

Dual CMOS output format ordering options support either complementary or in-phase signals for two identical frequency outputs. This feature enables replacement of multiple VCXOs with a single Si567 device.

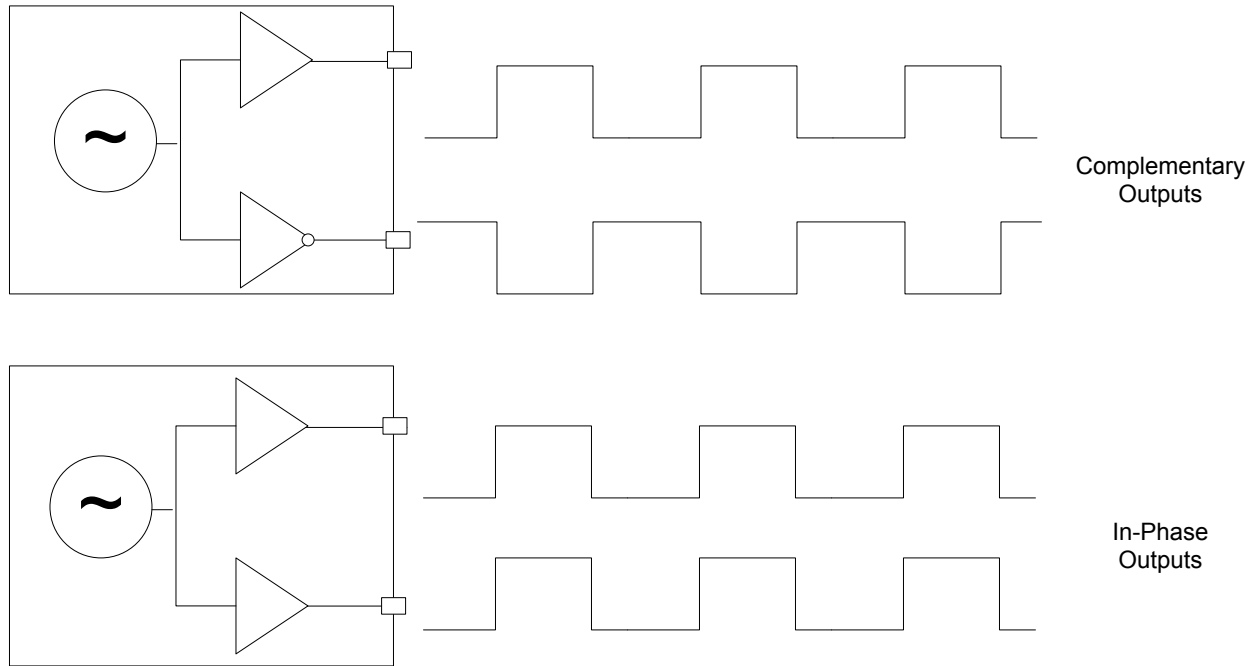


Figure 3.1. Integrated 1:2 CMOS Buffer Supports Complementary or In-Phase Outputs

4. Recommended Output Terminations

The output drivers support both AC-coupled and DC-coupled terminations as shown in figures below.

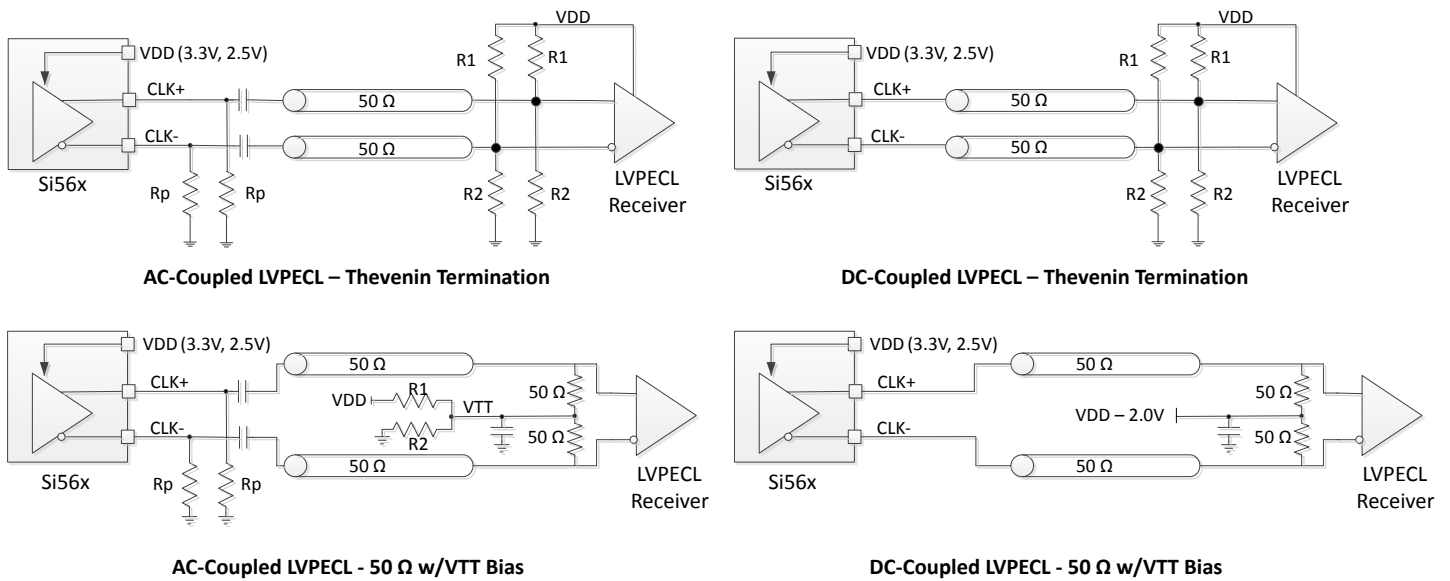


Figure 4.1. LVPECL Output Terminations

AC-Coupled LVPECL Termination Resistor Values			
VDD	R1	R2	Rp
3.3 V	82.5 Ω	127 Ω	130 Ω
2.5 V	62.5 Ω	250 Ω	90 Ω

DC-Coupled LVPECL Termination Resistor Values		
VDD	R1	R2
3.3 V	127 Ω	82.5 Ω
2.5 V	250 Ω	62.5 Ω

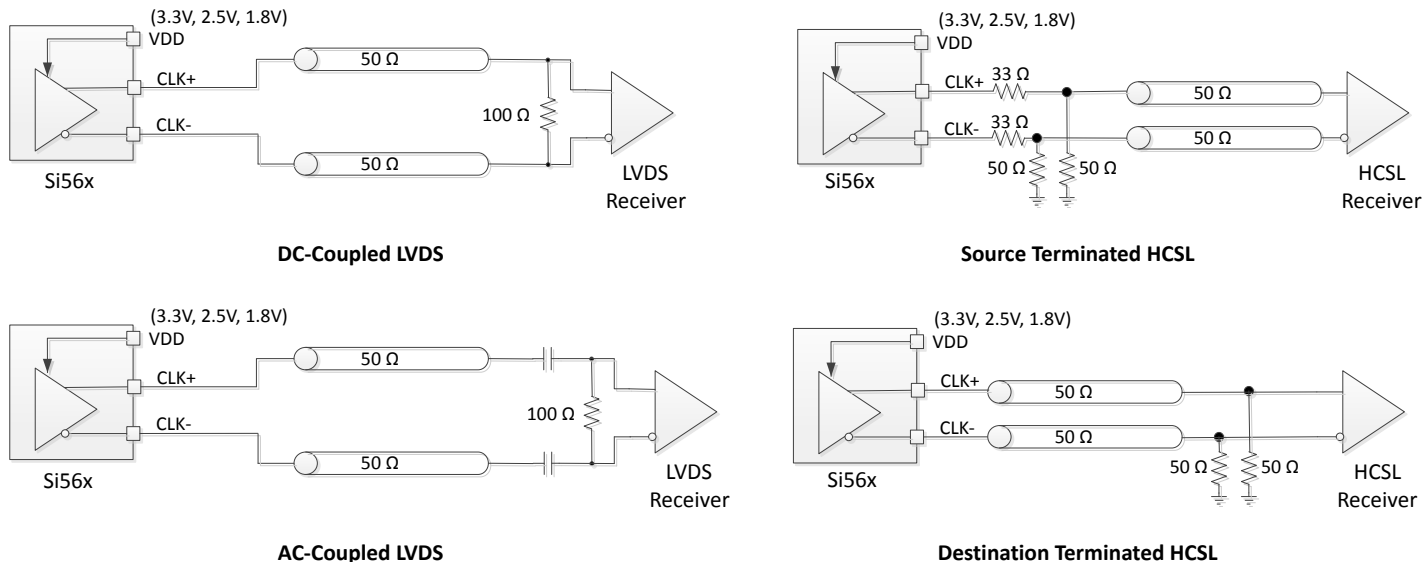


Figure 4.2. LVDS and HCSL Output Terminations

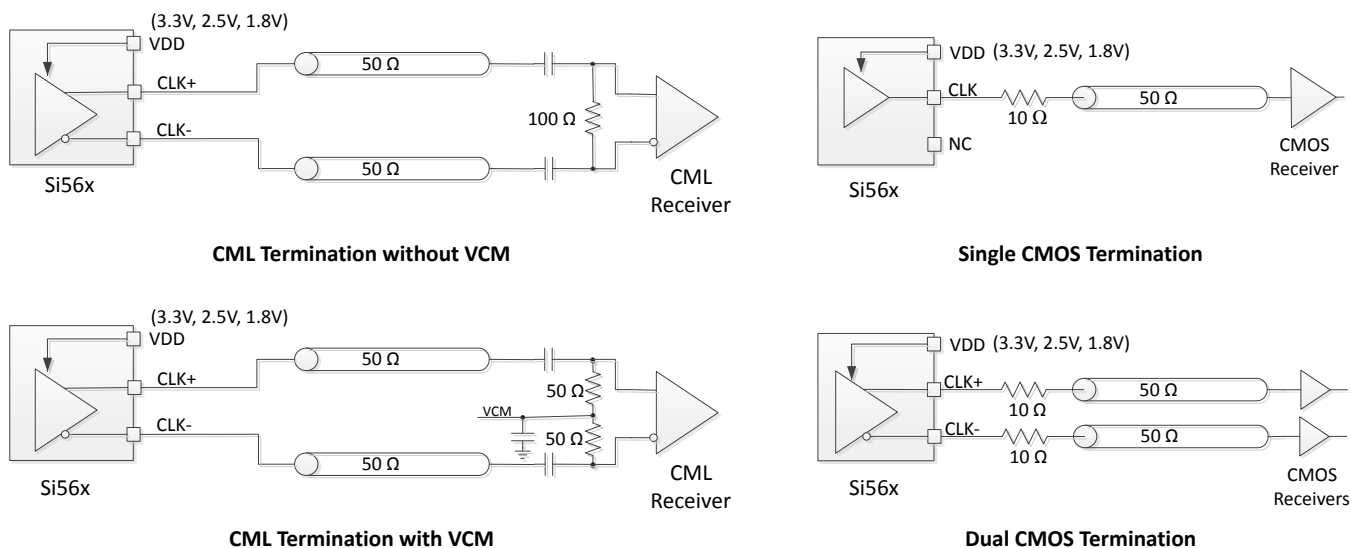


Figure 4.3. CML and CMOS Output Terminations

5. Package Outline

5.1 Package Outline (5x7 mm)

The figure below illustrates the package details for the 5x7 mm Si567. The table below lists the values for the dimensions shown in the illustration.

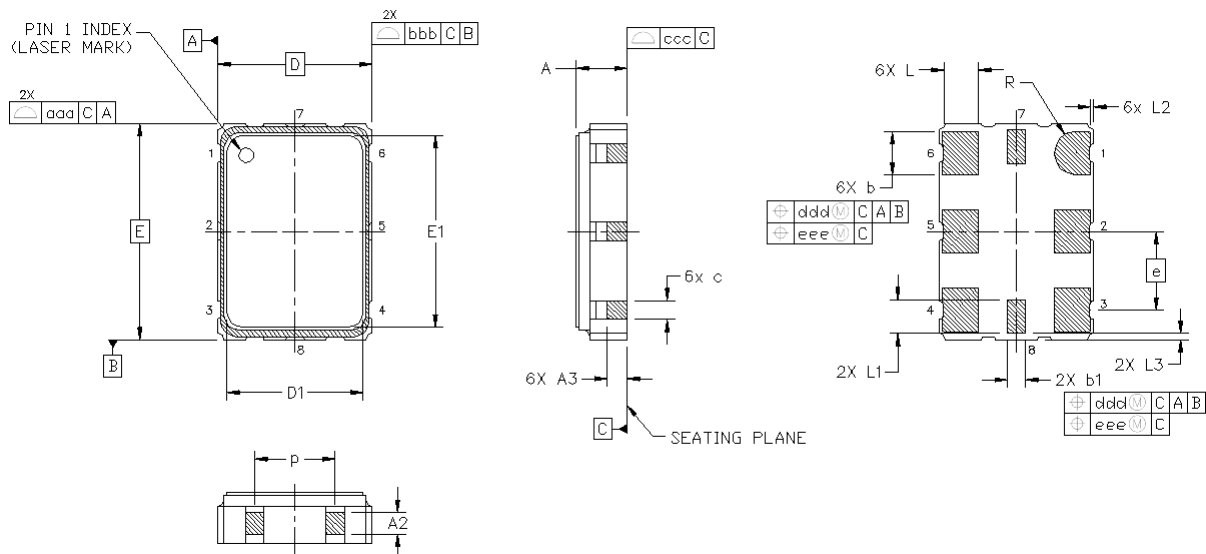


Figure 5.1. Si567 (5x7 mm) Outline Diagram

Table 5.1. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max	Dimension	Min	Nom	Max
A	1.07	1.18	1.33	L	1.07	1.17	1.27
A2	0.40	0.50	0.60	L1	1.00	1.10	1.20
A3	0.45	0.55	0.65	L2	0.05	0.10	0.15
b	1.30	1.40	1.50	L3	0.15	0.20	0.25
b1	0.50	0.60	0.70	p	1.70	--	1.90
c	0.50	0.60	0.70	R	0.70 REF		
D	5.00 BSC			aaa	0.15		
D1	4.30	4.40	4.50	bbb	0.15		
e	2.54 BSC			ccc	0.08		
E	7.00 BSC			ddd	0.10		
E1	6.10	6.20	6.30	eee	0.05		

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

5.2 Package Outline (3.2x5 mm)

The figure below illustrates the package details for the 3.2x5 mm Si567. The table below lists the values for the dimensions shown in the illustration.

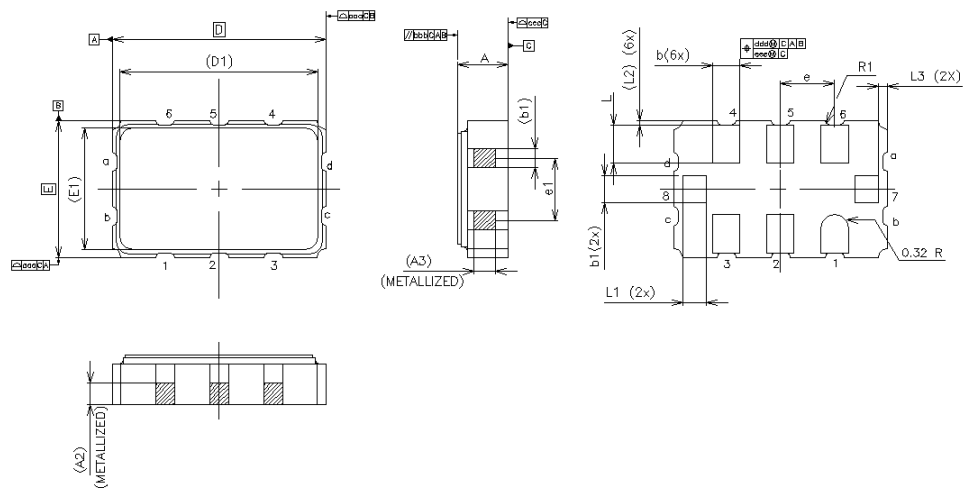


Figure 5.2. Si567 (3.2x5 mm) Outline Diagram

Table 5.2. Package Diagram Dimensions (mm)

Dimension	MIN	NOM	MAX	Dimension	MIN	NOM	MAX
A	1.02	1.17	1.33	E1	2.85 BSC		
A2	0.50	0.55	0.60	L	0.8	0.9	1.0
A3	0.45	0.50	0.55	L1	0.45	0.55	0.65
b	0.54	0.64	0.74	L2	0.05	0.10	0.15
b1	0.54	0.64	0.75	L3	0.15	0.20	0.25
D	5.00 BSC			aaa	0.15		
D1	4.65 BSC			bbb	0.15		
e	1.27 BSC			ccc	0.08		
e1	1.625 TYP			ddd	0.10		
E	3.20 BSC			eee	0.05		

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

5.3 Package Outline (2.5x3.2 mm)

The figure below illustrates the package details for the 2.5x3.2 mm Si567. The table below lists the values for the dimensions shown in the illustration.

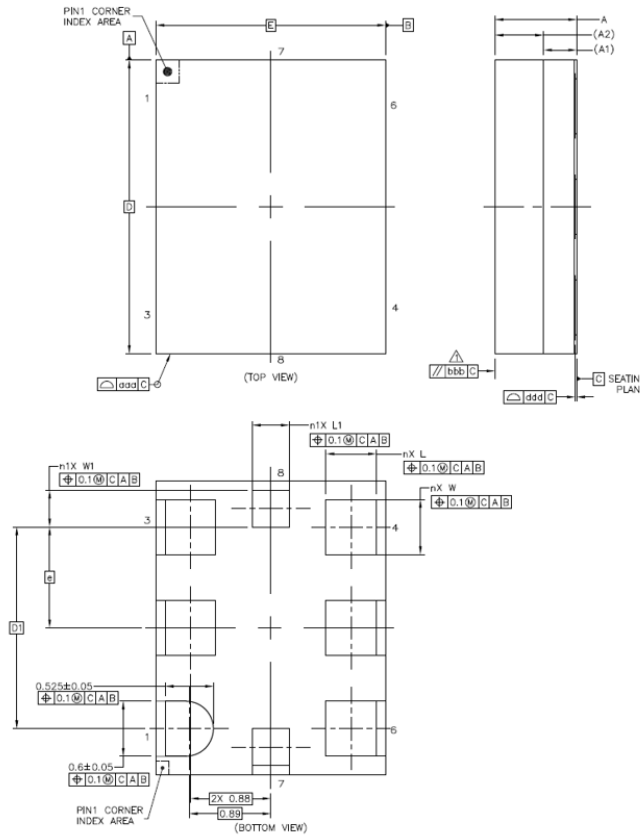


Figure 5.3. Si567 (2.5x3.2 mm) Outline Diagram

Table 5.3. Package Diagram Dimensions (mm)

Dimension	MIN	NOM	MAX	Dimension	MIN	NOM	MAX
A	0.85	0.90	1.00	L1	0.35	0.4	0.45
A1	0.36 REF			e	1.1 BSC		
A2	0.53 REF			n	5		
D	3.2 BSC			n1	2		
E	2.5 BSC			D1	2.2 BSC		
W	0.55	0.6	0.65	aaa	0.10		
L	0.5	0.55	0.6	bbb	0.10		
W1	0.35	0.4	0.45	ddd	0.08		

Notes:

1. The dimensions in parentheses are reference.
2. All dimensions shown are in millimeters (mm) unless otherwise noted.
3. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6. PCB Land Pattern

6.1 PCB Land Pattern (5x7 mm)

The figure below illustrates the 5x7 mm PCB land pattern for the Si567. The table below lists the values for the dimensions shown in the illustration.

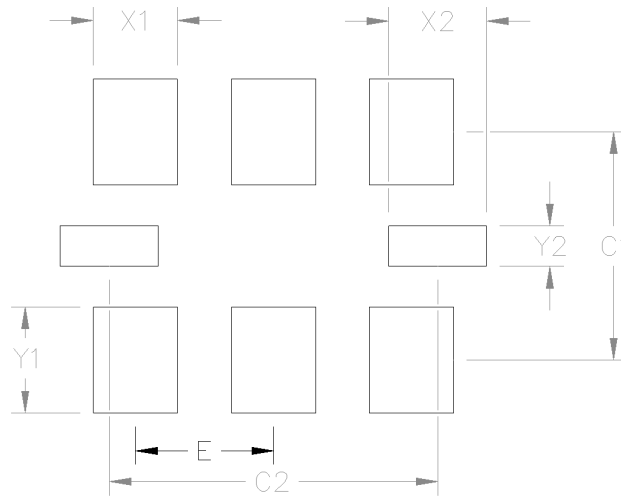


Figure 6.1. Si567 (5x7 mm) PCB Land Pattern

Table 6.1. PCB Land Pattern Dimensions (mm)

Dimension	(mm)	Dimension	(mm)
C1	4.20	Y1	1.95
C2	6.05	X2	1.80
E	2.54	Y2	0.75
X1	1.55		

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.2 PCB Land Pattern (3.2x5 mm)

The figure below illustrates the 3.2x5.0 mm PCB land pattern for the Si567. The table below lists the values for the dimensions shown in the illustration.

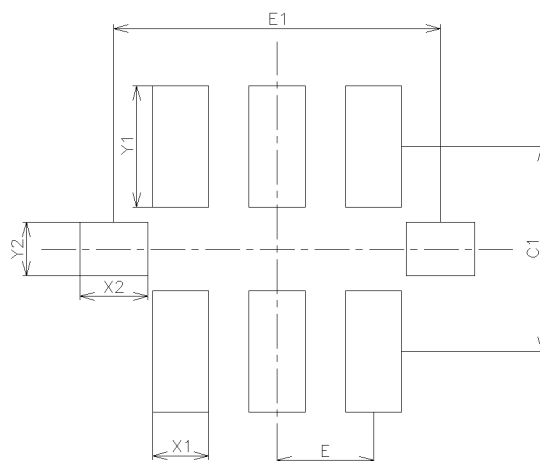


Figure 6.2. Si567 (3.2x5 mm) PCB Land Pattern

Table 6.2. PCB Land Pattern Dimensions (mm)

Dimension	(mm)	Dimension	(mm)
C1	2.70	X2	0.90
E	1.27	Y1	1.60
E1	4.30	Y2	0.70
X1	0.74		

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μ m minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.3 PCB Land Pattern (2.5x3.2 mm)

The figure below illustrates the 2.5x3.2 mm PCB land pattern for the Si567. The table below lists the values for the dimensions shown in the illustration.

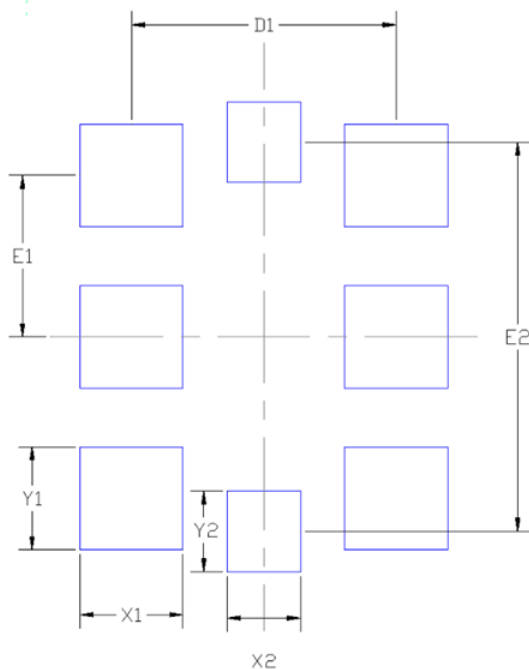


Figure 6.3. Si567 (2.5x3.2 mm) PCB Land Pattern

Table 6.3. PCB Land Pattern Dimensions (mm)

Dimension	Description	Value (mm)
X1	Width - leads on long sides	0.7
Y1	Height - leads on long sides	0.7
X2	Width - single leads on short sides	0.5
Y2	Height - single leads on short sides	0.55
D1	Pitch in X directions of XL, Y1 leads	1.80
E1	Lead pitch X1, Y1 leads	1.10
E2	Lead pitch X2, Y2 leads	2.65

Dimension	Description	Value (mm)
<p>Notes:</p> <p>General</p> <ol style="list-style-type: none"> 1. All dimensions shown are in millimeters (mm) unless otherwise noted. 2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification. 3. This Land Pattern Design is based on the IPC-7351 guidelines. 4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm. <p>Solder Mask Design</p> <ol style="list-style-type: none"> 1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad. <p>Stencil Design</p> <ol style="list-style-type: none"> 1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release. 2. The stencil thickness should be 0.125 mm (5 mils). 3. The ratio of stencil aperture to land pad size should be 0.8:1 for the pads. <p>Card Assembly</p> <ol style="list-style-type: none"> 1. A No-Clean, Type-3 solder paste is recommended. 2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components. 		

7. Top Markings

7.1 Top Marking (5x7 and 3.2x5 Packages)

The figure below illustrates the mark specification for the Si567 5x7 and 3.2x5 package sizes. The table below lists the line information.

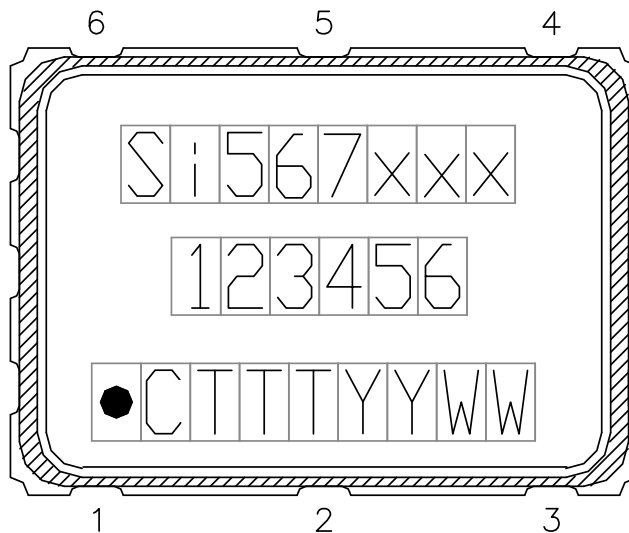


Figure 7.1. Mark Specification

Table 7.1. Si567 Top Mark Description

Line	Position	Description
1	1–8	"Si567", xxx = Ordering Option 1, Option 2, Option 3 (e.g. Si567AAA)
2	1–6	Frequency Code (6-digit custom code as described in the Ordering Guide)
3	Trace Code	
	Position 1	Pin 1 orientation mark (dot)
	Position 2	Product Revision (C)
	Position 3–5	Tiny Trace Code (3 alphanumeric characters per assembly release instructions)
	Position 6–7	Year (last two digits of the year), to be assigned by assembly site (ex: 2017 = 17)
	Position 8–9	Calendar Work Week number (1–53), to be assigned by assembly site

7.2 Top Marking (2.5x3.2 Package)

The figure below illustrates the mark specification for the Si567 2.5x3.2 package sizes. The table below lists the line information.

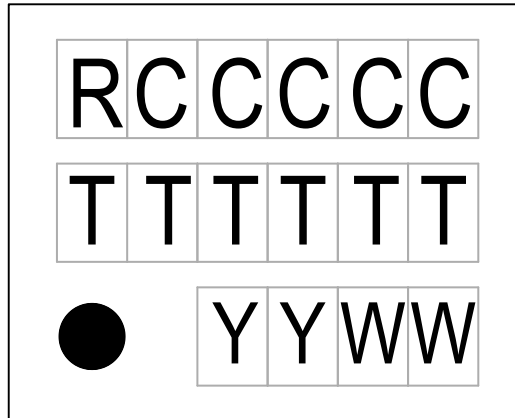


Figure 7.2. Mark Specification

Table 7.2. Si567 Top Mark Description

Line	Position	Description
1	1–6	R = Si567, CCCCC = Custom Mark Code
2	Trace Code	
	1–6	Six-digit trace code per assembly release instructions
3	Position 1	Pin 1 orientation mark (dot)
	Position 2–3	Year (last two digits of the year), to be assigned by assembly site (exp: 2017 = 17)
	Position 4–5	Calendar Work Week number (1–53), to be assigned by assembly site

8. Revision History

Revision 206624A

May, 2023

- Updated Min and Nom package diagram dimensions specs in [5.3 Package Outline \(2.5x3.2 mm\)](#).

Revision 1.3

June, 2021

- Updated Ordering Guide and Top Mark for Rev C silicon.
- Added HCSL-Fast (faster t_R/t_F) ordering option.
- Updated Table 2.1, Powerup VDD Ramp Rate.

Revision 1.2

September, 2020

- Added 2.5 x 3.2 mm package option.
- Updated Table 2.1, Powerup VDD Ramp Rate and LVDS Swing.

Revision 1.0

June, 2018

- Initial draft



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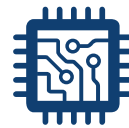
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